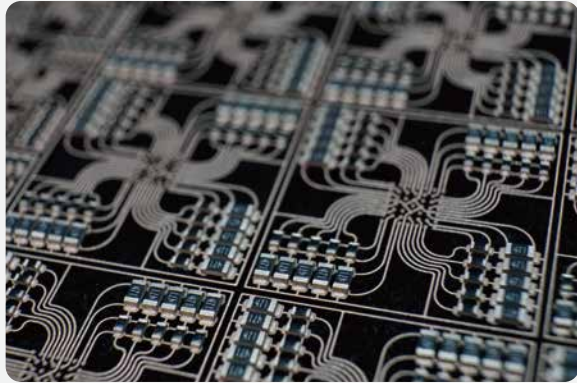


Low Temperature Curable SMT Paste

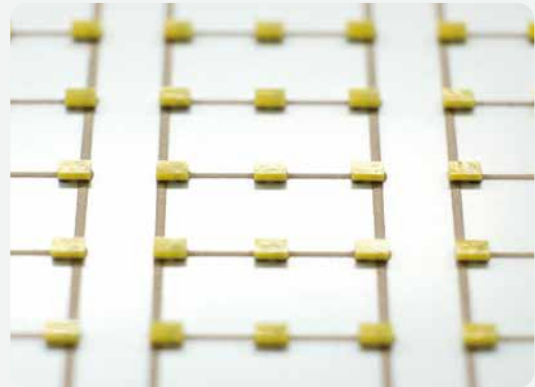
Suitable to low heat resistance substrates

Applications

Chip mounting



e.g. : Glass wafers



e.g. : LED chip mounting on polyimide substrates

Features

- Low temperature process
- Excellent adhesion
- Excellent stress absorption



0201 chip mounting

Product line-up & properties

Product			AE8010
Viscosity	BH type	dPa·s	1,000 - 1,500
Curing conditions			120°C × 30min.
Volume resistivity (Representative value)		Ω·cm	1.5E-04
Thermal conductivity		W/m·k	10

